

# 1.5V Drive Pch+Pch MOSFET

## QS6J11

### ●Structure

Silicon P-channel MOSFET

### ●Features

- 1) Two Pch MOSFET transistors in a single TSMT6 package.
- 2) Low on-state resistance with a fast switching.
- 3) Low voltage drive (1.5V).

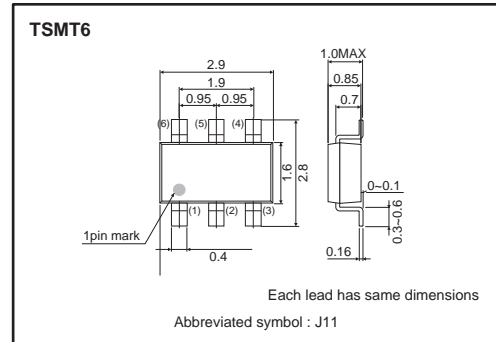
### ●Applications

Switching

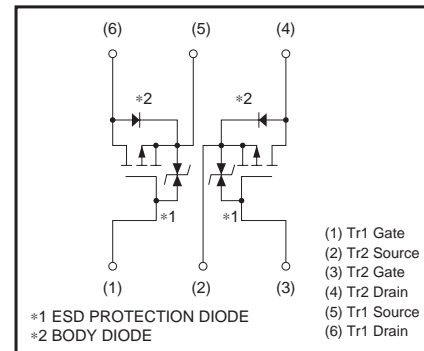
### ●Packaging specifications

Type	Package	Taping
	Code	TR
	Basic ordering unit (pieces)	3000
QS6J11		○

### ●Dimensions (Unit : mm)



### ●Inner circuit



### ●Absolute maximum ratings (Ta=25°C)

<It is the same ratings for Tr1 and Tr2>

Parameter	Symbol	Limits	Unit
Drain-source voltage	$V_{DSS}$	-12	V
Gate-source voltage	$V_{GSS}$	±10	V
Drain current	Continuous	$I_D$	±2 A
	Pulsed	$I_{DP}$ *1	±8 A
Source current (Body diode)	Continuous	$I_S$ *1	-0.75 A
	Pulsed	$I_{SP}$	-8 A
Total power dissipation	$P_D$ *2	1.25	W / TOTAL
		0.9	W / ELEMENT
Channel temperature	$T_{ch}$	150	°C
Range of Storage temperature	$T_{stg}$	-55 to +150	°C

\*1  $P_w \leq 10\mu s$ , Duty cycle  $\leq 1\%$   
\*2 Mounted on a ceramic board

### ●Thermal resistance

Parameter	Symbol	Limits	Unit
Channel to ambient	$R_{th}(ch-a)$ *	100	°C / W / TOTAL
		139	°C / W / ELEMENT

\* Mounted on a ceramic board

●Electrical characteristics (Ta=25°C)

<It is the same characteristics for Tr1 and Tr2 MOS FET>

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	I <sub>GSS</sub>	–	–	±10	μA	V <sub>GS</sub> =±10V, V <sub>DS</sub> =0V
Drain-source breakdown voltage	V <sub>(BR) DSS</sub>	–12	–	–	V	I <sub>D</sub> = –1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	I <sub>DSS</sub>	–	–	–1	μA	V <sub>DS</sub> = –12V, V <sub>GS</sub> =0V
Gate threshold voltage	V <sub>GS(th)</sub>	–0.3	–	–1.0	V	V <sub>DS</sub> = –6V, I <sub>D</sub> = –1mA
Static drain-source on-state resistance	R <sub>DS(on)</sub> *	–	75	105	mΩ	I <sub>D</sub> = –2A, V <sub>GS</sub> = –4.5V
		–	105	145	mΩ	I <sub>D</sub> = –1A, V <sub>GS</sub> = –2.5V
		–	150	225	mΩ	I <sub>D</sub> = –1A, V <sub>GS</sub> = –1.8V
		–	200	400	mΩ	I <sub>D</sub> = –0.4A, V <sub>GS</sub> = –1.5V
Forward transfer admittance	Y <sub>fs</sub>   *	2	–	–	S	V <sub>DS</sub> = –6V, I <sub>D</sub> = –2A
Input capacitance	C <sub>iss</sub>	–	770	–	pF	V <sub>DS</sub> = –6V
Output capacitance	C <sub>oss</sub>	–	75	–	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	C <sub>rss</sub>	–	60	–	pF	f=1MHz
Turn-on delay time	t <sub>d(on)</sub> *	–	10	–	ns	V <sub>DD</sub> ≐ –6V
Rise time	t <sub>r</sub> *	–	17	–	ns	I <sub>D</sub> = –1A V <sub>GS</sub> = –4.5V
Turn-off delay time	t <sub>d(off)</sub> *	–	65	–	ns	R <sub>L</sub> ≐6Ω
Fall time	t <sub>f</sub> *	–	35	–	ns	R <sub>G</sub> =10Ω
Total gate charge	Q <sub>g</sub> *	–	6.5	–	nC	V <sub>DD</sub> ≐ –6V R <sub>L</sub> ≐3Ω
Gate-source charge	Q <sub>gs</sub> *	–	1.3	–	nC	I <sub>D</sub> = –2A R <sub>G</sub> =10Ω
Gate-drain charge	Q <sub>gd</sub> *	–	0.8	–	nC	V <sub>GS</sub> = –4.5V

\*Pulsed

●Body diode (Source-drain) (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V <sub>SD</sub> *	–	–	–1.2	V	I <sub>S</sub> = –2A, V <sub>GS</sub> =0V

\*Pulsed

●Electrical characteristic curves

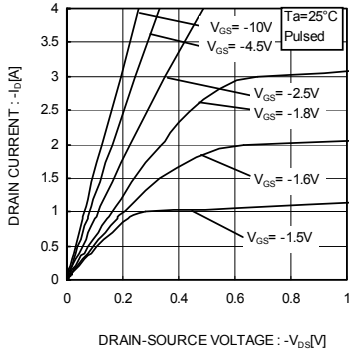


Fig.1 Typical Output Characteristics( I )

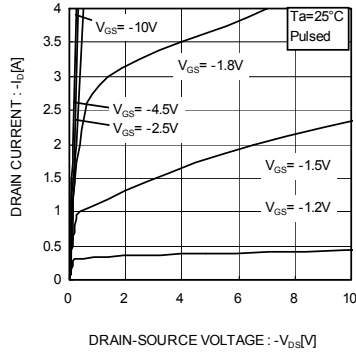


Fig.2 Typical Output Characteristics( II )

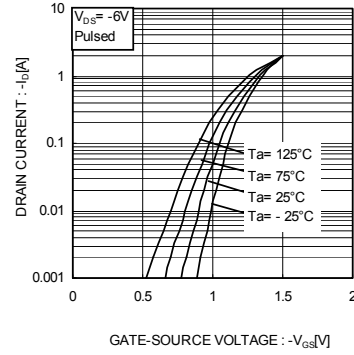


Fig.3 Typical Transfer Characteristics

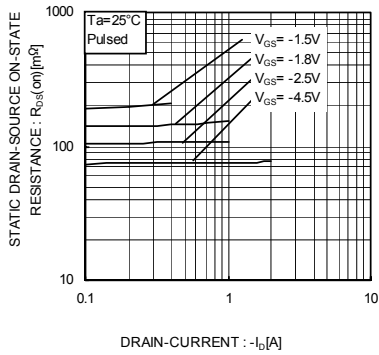


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current( I )

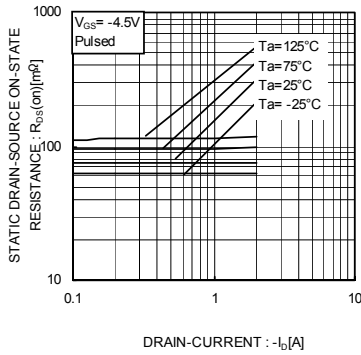


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current( II )

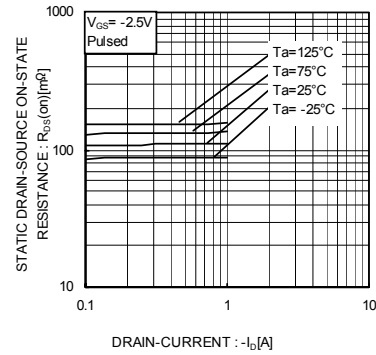


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current( III )

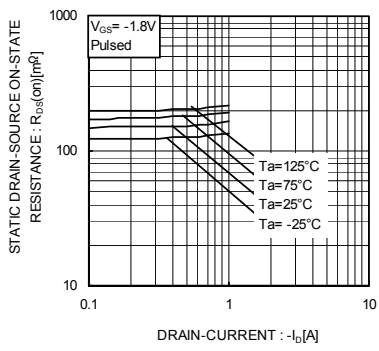


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current(IV)

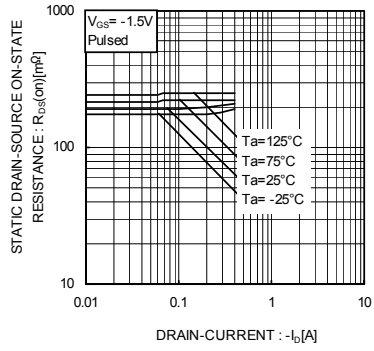


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current( V )

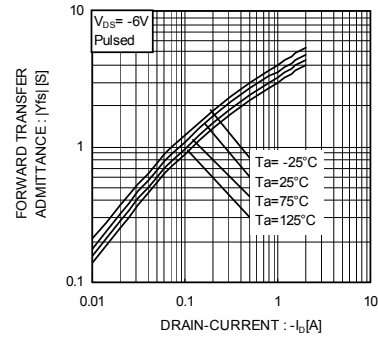


Fig.9 Forward Transfer Admittance vs. Drain Current

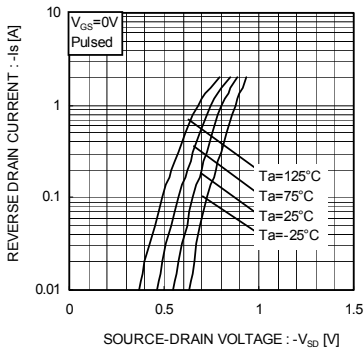


Fig.10 Reverse Drain Current vs. Source-Drain Voltage

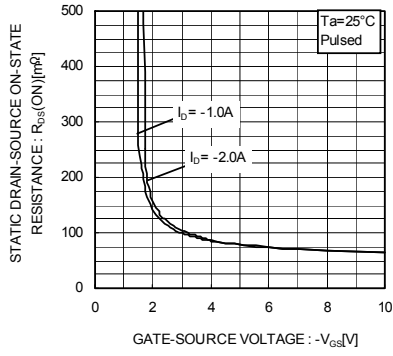


Fig.11 Static Drain-Source On-State Resistance vs. Gate Source Voltage

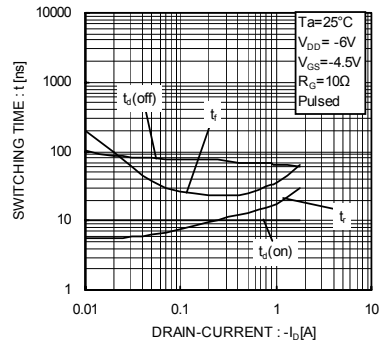


Fig.12 Switching Characteristics

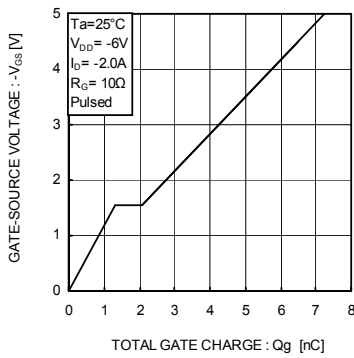


Fig.13 Dynamic Input Characteristics

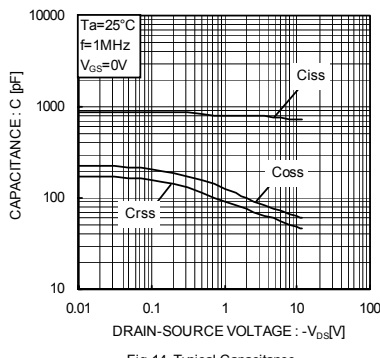


Fig.14 Typical Capacitance vs. Drain-Source Voltage

●Measurement circuits

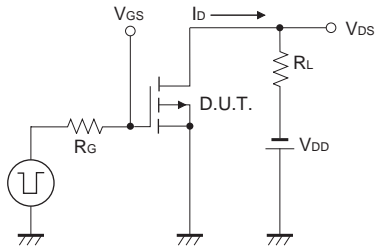


Fig.1-1 Switching Time Measurement Circuit

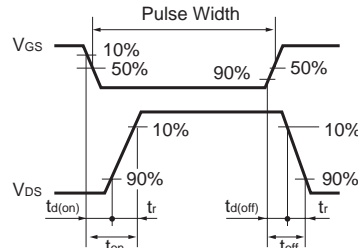


Fig.1-2 Switching Waveforms

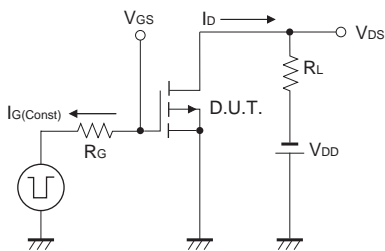


Fig.2-1 Gate Charge Measurement Circuit

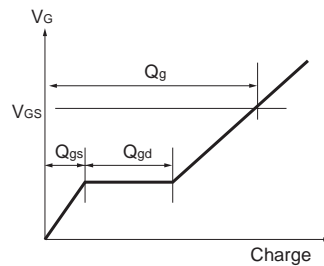


Fig.2-2 Gate Charge Waveform

●Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

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